INSULATED METAL SUBSTRATE AND METHOD OF FORMING THE SAME

ABSTRACT

An insulated metal substrate (1) for use in metal clad printed circuit board, the insulated metal substrate (1) comprises a metal substrate (10), an electrically insulating layer (12) disposed on the metal substrate (10), and an electrically conducting layer (14) capable of interconnecting electronic power components (24) such as light emitting devices or light emitting diodes (LEDs), the electrically conducting layer (14) disposed on the electrically insulating layer (12). The metal substrate (10) comprises a base metal (10a) and a dissimilar overlaying metal (10b) disposed on the base metal (10a). Method of forming the insulated metal substrate (1) is also provided.

FIGURE 1